

L Number	Hits	Search Text	DB	Time stamp
1	225	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST	USPAT; EPO; JPO; DERWENT	2003/11/07 14:49
2	108	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and pad\$1	USPAT; EPO; JPO; DERWENT	2003/11/07 14:49
3	5	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and pad\$1 and ((plurality or multiple) adj2 chip\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:50
4	17	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and ((plurality or multiple) adj2 chip\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:50
5	50	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test adj3 result\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:51
6	88	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:51
7	84	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC or chip\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:52
8	84	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:52
9	0	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and (integrally adj3 sealed)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:53
10	8	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and integrally	USPAT; EPO; JPO; DERWENT	2003/11/07 14:54
11	1	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and integrally and (714/724.ccls.)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:54
12	0	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and integrally and (714/727.ccls.)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:54
13	19	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and (714/727.ccls.)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:54
14	10	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and (714/724.ccls.)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:55
15	10	((test adj3 input) or TDI) and (TDO or (test adj3 output)) and TCK and TMS and TRST and (test near3 result\$1) and ((semiconductor adj2 device) or IC\$1 or chip\$1) and (714/724.ccls.) and (control adj3 signal\$1)	USPAT; EPO; JPO; DERWENT	2003/11/07 14:55